



## Material Composition Sheet

**Product:** GS1510-CQRE3  
**Package Type:** DQFP-128 pin (66/tray)  
**Manufacturer:** Gennum Corporation

**Date:** 05-Mar-2007

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		29.91	Al	0.18	0.60	6018
			Si	29.73	99.39	993982
			Sub-total:	29.91	99.99	1000000
Die Attach	CRM 1076DS	3.81	Ag	2.89	75.85	758530
			Epoxy Resin	0.49	12.86	128609
			Epoxy Silane	0.05	1.31	13123
			Phenol Resin	0.11	2.88	28871
			t-Butylphenylglycidil ether	0.27	7.08	70866
			Sub-total:	3.81	99.98	999999
Lead Finish External		31.50	Sn	31.50	100.00	1000000
			Sub-total:	31.50	100.00	1000000
Lead Finish Internal		1.15	Ag	1.15	100.00	1000000
			Sub-total:	1.15	100.00	1000000
Leadframe	OLIN 7025	270.80	Cu	260.51	96.20	962001
			Mg	0.41	0.15	1514
			Ni	8.12	2.99	29985
			Si	1.76	0.64	6499
			Sub-total:	270.80	99.98	999999
Marking Ink	Teca 261	0.10		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound	EME G700	1411.57	Carbon Black	7.06	0.50	5002
			Epoxy Resin	112.93	8.00	80003
			Phenol Resin	91.75	6.49	64999
			SiO2	1199.83	84.99	849997
			Sub-total:	1411.57	99.98	1000001
Wires	MGM 7	2.40	Au	2.40	100.00	1000000
			Sub-total:	2.40	100.00	1000000
<b>Total:</b>		<b>1751.24</b>				

### GENNUM CORPORATION

Mailing Address: P.O. Box 489, Str. A, Burlington, Ontario, Canada L7R 3Y3  
 Shipping Address: 970 Fraser Drive, Burlington, Ontario, Canada L7L 5P5  
 Tel. +1 (905) 632-2996 Fax. +1 (905) 632-5946

[www.gennum.com](http://www.gennum.com)

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